PATENT

Docket No.: JCLA8533-D2
Date: January 09, 2004

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) **as a divisional application** of prior application No.**10/055,568** filed on **January 22, 2002.**

Prior application information: **Examiner:** MITCHELL, JAMES M. ; **Group Art Unit:** 2827

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): MOU-SHIUNG LIN ;
JIN-YUAN LEE ;
CHING-CHENG HUENG ;

For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

Enclosed are:

(X) Specification in FOURTY-ONE (41) pages.
(X) SIXTEEN (16) sheets of Drawings.
(X) Preliminary Amendment.
(X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
(X) **Applicant claims small entity status. See 37 CFR 1.27.**
(X) Return prepaid postcard.

CLAIMS AS FILED

FOR	**NUMBER FILED**	**NUMBER EXTRA**	**RATE**	**FEE**
Basic Fee			$ 385	$ 385
Total Claims	27 - 20 =	7 ×	$ 9	$ 63
Independent Claims	1 - 3 =	0 ×	$ 43	$ 0
If application contains any multiple dependent claims(s), then add			$ 145	$ 0
For a Small Entity:	**TOTAL FILING FEE**			**$ 448**

(X) A check in the amount of $ 448 to cover the filing fee is enclosed.
(X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA8533-D2). A duplicate copy of this sheet is enclosed.

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

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Inventor(s)	:	MOU-SHIUNG LIN ; JIN-YUAN LEE ; CHING-CHENG HUENG ;
For	:	INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF MANUFACTURING THE SAME
"Express Mail" Mailing Label No.	:	EV 300987573 US
Date of Deposit	:	January 09, 2004

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 41 page(s); 16 sheets of drawing(s); Copy of Declaration and Power of Attorney from prior application; Preliminary Amendment; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313-1450

Michelle Chang